

What is claimed is:

1. A liquid cooling system, comprising:

a heat-receiving jacket for absorbing heat of a heat-generation element through a liquid flowing with an inside
5 thereof;

a radiator for radiation heat from a surface thereof; and

a pump for transporting said liquid absorbing the heat therein to said radiator, wherein

said pump is connected to said radiator, directly.

10 2. A liquid cooling system, comprising:

a heat-receiving jacket for absorbing heat generated from a semiconductor through a liquid, which is enclosed within an inside
thereof;

15 a radiator being connected with said heat-receiving jacket through a flexible conduit therebetween;

a tank being connected to said radiator through a conduit;
and

a pump for circulating said liquid, further comprising:

20 a plural number of fins being attached onto a metal conduit of said radiator passing the liquid passes therethrough, wherein

said pump is connected to said tank, which is connected to said metal conduit, directly.

3. The liquid cooling system, as described in the claim 2, wherein:

25 said radiator has at least two (2) pieces of metal conduits, whereby forming a suction conduit of said pump from one of said

metal conduits, while a discharge conduit to said heat-receiving jacket from the other of said conduits, and said suction/discharge conduits are communicated with an inside of said tank.

4. The liquid cooling system, as described in the claim
5 2, wherein:

a suction port and a discharge port are provided on said pump, and those ports are connected with said tank, being inserted into port insertion openings provided thereon.

5. The liquid cooling system, as described in the claim
10 2, wherein:

an inside of said tank is divided into two (2) spaces with a partition plate, into one thereof being opened the suction port of said pump and said suction conduit while into the other thereof being opened said discharge port and said discharge conduit.

6. The liquid cooling system, as described in the claim
15 2, wherein:

a partition plate for separating an inside of said tank into two (2) is formed to be about "S" in shape thereof.

7. The liquid cooling system, as described in the claim
20 5, wherein:

an air storage portion is provided in each of the spaces of said tank.

8. A liquid cooling system, comprising:

a heat-receiving jacket for absorbing heat generated from
25 a semiconductor element through a liquid enclosed in an inside thereof;

a radiator being connected to said heat-receiving jacket through a conduit;

a tank being connected to said radiator through a conduit;
and

a pump for circulating said liquid, wherein:

5 a member building up said cooling system has a suction port
and a discharge port, and is connected by inserting those ports
into port insertion openings, which are provide in said conduits.